

Features

- ☐ IEC61000-4-2 (ESD) +/-30kV (air),
+/-30KV(contact)
- IEC61000-4-4 (EFT) 80A (5/50 ns)
- ☐ Peak Pulse Current(tp=8/20us) 25A
- ☐ Protects one I/O line
- ☐ Working voltages : 12.0V
- ☐ Low leakage current

Description

The TS1231LDX is designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. These devices are ideal for situations where board space is at a premium. This series has been specifically designed to protect sensitive components which are connected to power data and transmission lines from overvoltage caused by ESD(electrostatic discharge), CDE (Cable Discharge Events), and EFT (electrical fast transients).

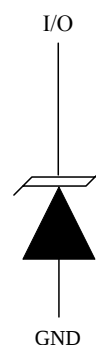
Applications

- ☐ Cell Phone Handsets and Accessories
- ☐ Microprocessor based equipment
- ☐ Personal Digital Assistants (PDA's)
- ☐ Notebooks, Desktops, and Servers
- ☐ Portable Instrumentation
- ☐ Networking and Telecom
- ☐ Serial and Parallel Ports.
- ☐ Peripherals

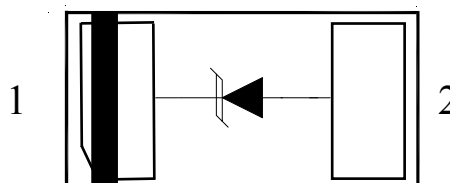
Mechanical Characteristics

- ☐ DFN1610-2L package
- ☐ Flammability Rating: UL 94V-0
- ☐ Packaging: Tape and Reel
- ☐ High temperature soldering guaranteed: 260°C/10s
- ☐ Reel size: 7 inch
- ☐ ROHS compliant
- ☐ MSL-1

Circuit Diagram



Pin Configuration



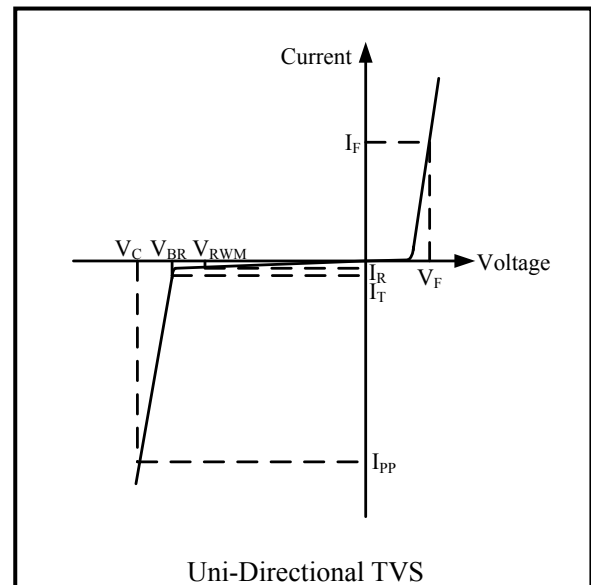
DFN1610-2L
(Top View)

Absolute Maximum Rating

Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	± 30 ± 30	kV
I_{PP}	Peak Pulse Current(8/20us)	25	A
T_{OPT}	Operating Temperature	-55/+150	°C
T_{STG}	Storage Temperature	-55/+150	°C
T_L	Lead Soldering Temperature	260 (10 sec.)	°C

Electrical Characteristics (T = 25°C)

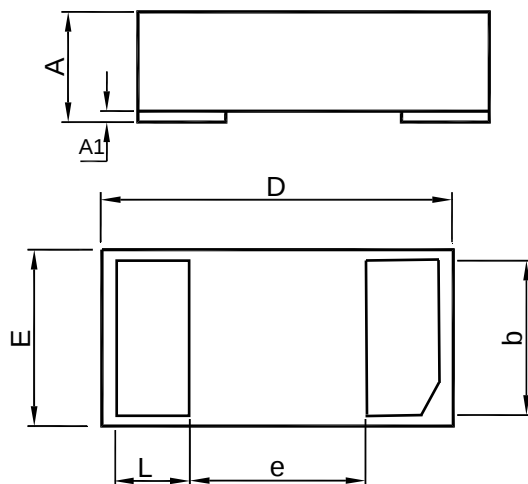
Symbol	Parameter
V_{RWM}	Nominal Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{t1}	Trigger Voltage
I_{t1}	Trigger Current @ V_{t1}
V_h	Holding Voltage
I_h	Holding Current @ V_h
V_C	Clamping Voltage @ I_{PP}
V_{CR}	Reverse Clamping Voltage @ I_{PP}
I_{PP}	Maximum Peak Pulse Current
C_{ESD}	Parasitic Capacitance



Symbol	Test Condition	Minimum	Typical	Maximum	Units
V_{RWM}				12.0	V
I_R	$V_{RWM} = 12.0V, T = 25^\circ C$		0.01	0.1	μA
V_{BR}	$I_T = 1mA$	13.3			V
V_F	$I_T = 1mA$			0.9	V
V_C	$I_{PP} = 1A, t_p = 8/20\mu s$			18.0	V
V_C	$I_{PP} = 5A, t_p = 8/20\mu s$			20.0	V
V_C	$I_{PP} = 25A, t_p = 8/20\mu s$			30.0	V
C_{ESD}	$V_R = 0V, f = 1MHz$			160	pF

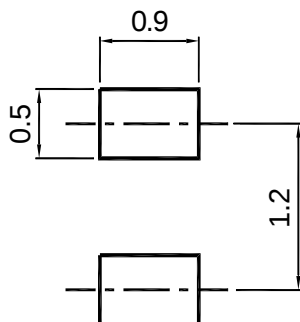
Package Outline Demensions

☐ DFN1610-2L Package

☐ MSL-1


UNIT	A	A1	b	D	E	e	L
mm	0.55 0.45	0.05 0	0.85 0.75	1.65 1.55	1.05 0.95	0.75 0.65	0.45 0.35

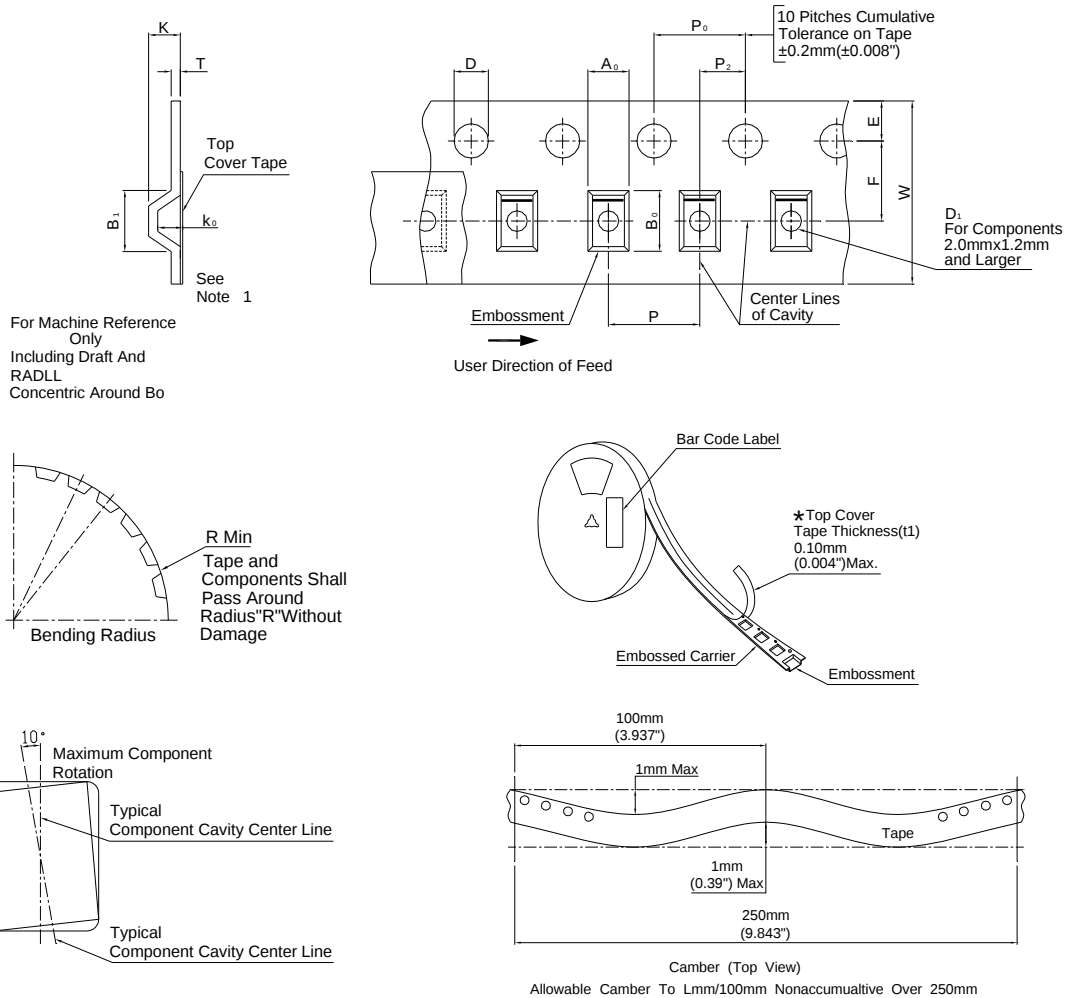
Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
DFN1610-2L	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Tape and Reel Specification



Dimensions

Tape Size	B ₁ Max.	D	D ₁	E	F	K	P ₀	P ₂	R Min.	T Max.	W Max.
8 mm	4.55mm (0.179")	1.5 +0.1mm -0.0 (0.059")	1.0 mm Min (0.039")	1.75± 0.1 mm (0.069± 0.004")	3.5 ± 0.05 mm (0.138 ± 0.002")	2.4 mm Max (0.094")	4 ± 0.1 mm (0.157 ± 0.004")	2 ± 0.1 mm (0.079 ± 0.002")	25 mm (0.98")	0.6 mm (0.024")	8.3 mm (0.327")
12 mm	8.2mm (0.323")	1.5 +0.1mm -0.0 (0.059")	1.5 mm Min (0.060")	1.75± 0.1 mm (0.069± 0.004")	5.5 ± 0.05 mm (0.217 ± 0.002")	6.4 mm Max (0.252")	4 ± 0.1 mm (0.157 ± 0.004")	2 ± 0.05 mm (0.079 ± 0.002")	30 mm (1.18")		12 ± 0.30 mm (0.47±0.012")

Metric dimensions govern-English are in parentheses for reference only.

Note 1: A₀, B₀, and K₀ are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min. to 0.5 mm max.

The component cannot rotate more than 10° within the determined cavity.

If B₁ exceeds 4.2 mm(0.165") for 8 mm embossed tape, the tape may not feed through all tape feeders.

Marking Codes



Note:

(1) "SB3D" is part number, fixed

Ordering Information

Part Number	Working Voltage	Quantity Per Reel	Reel Size
TS1231LDX	12.0V	3,000	7 Inch

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